



Product data sheet

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SMB

Features

Low capatcitance Cannot be damaged by voltage Will not fatigue Eliminate voltage overshoot Glass passivated junction Halogen free and RoHS compliant

Mechanical Data

CASE: SMB(DO-214AA) Molded Plastic UL Flammability Classification Rating 94V0 Mounting Position:Any

Maximum Ratings & Thermal Characteristics

(Ratings at 25° C ambient temperature unless otherwise specified.)

Parameter	Symbol	Value	Units	Remarks
Peak Pulse Voltage	V _{PP}	4000	V	10/700us
Peak Pulse Current	IPP	80	А	10/1000us
Peak Pulse Current	I _{PK}	250	А	8/20us
Peak One-cycle Surge Current	I _{TSM}	25	А	60Hz
Rate of Rise of Current	di/dt	500	A/us	
Typical Thermal Resistance Junction to Lead	R _{eJL}	20	°C/W	
Typical Thermal Resistance Junction to Ambient	R _{eja}	100	°C/W	
Operating Temperature Range	TJ	-40 to 150	°C	
Storage Temperature Range	T _{STG}	-55 to 150	°C	

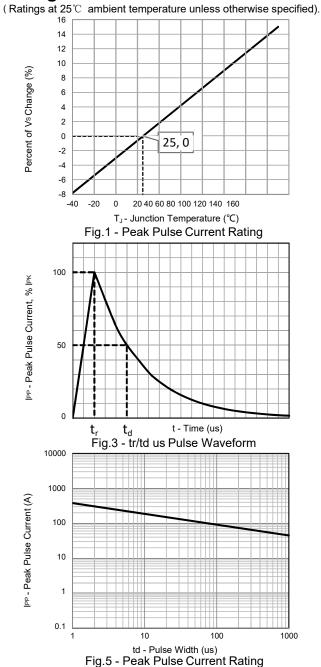
Electrical Characteristics

(Ratings at 25 $^\circ\!\mathrm{C}$ $\,$ ambient temperature unless otherwise specified).

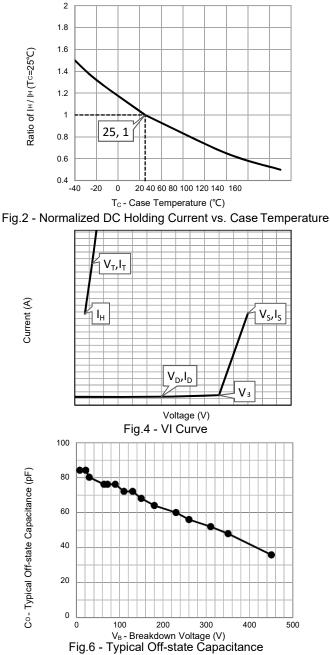
		V _S @100KV/S	I _{S_LMT}	V _T @ I _T	Iτ	$I_D @ V_D$	VD	Co@1MHz,2VDC	Iн
P/N	Mark	V	mA	V	А	uA	V	pF	mA
		MAX		MAX		MAX		TYP	MAX
P4200SB-MS	P42B XXXX	520	800	4	2.2	5	400	36	100







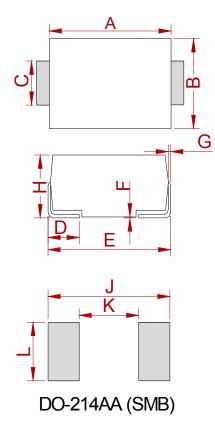
Ratings and Characteristic Curves





P4200SB-MS

PACKAGE MECHANICAL DATA



	Dimensions				
Ref.	Millir	neters	Inches		
	Min.	Max.	Min.	Max.	
Α	4.25	4.75	0.167	0.187	
В	3.30	3.94	0.130	0.155	
С	1.85	2.21	0.073	0.087	
D	0.76	1.52	0.030	0.060	
E	5.08	5.59	0.200	0.220	
F	0.051	0.203	0.002	0.008	
G	0.15	0.31	0.006	0.012	
Н	2.11	2.44	0.083	0.096	
J	6.80		0.270		
K		2.60		0.100	
L	2.40		0.090		

REEL SPECIFICATION

	DKO	
P/N	PKG	QIY
P4200SB-MS	SMB	3000



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